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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.
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09/383,876    08/26/99    RAEDER    C    AMDA.316PA

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EXAMINER

NGUYEN, D

ART UNIT

PAPER NUMBER

3723

DATE MAILED:

10/19/00

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**Please find below and/or attached an Office communication concerning this application or proceeding.**

**Commissioner of Patents and Trademarks**

# Office Action Summary

Application No.  
**09/383,876**

Applicant(s)  
**Christopher H. Raeder**

Examiner  
**Dung Van Nguyen**

Group Art Unit  
**3723**



☒ Responsive to communication(s) filed on 17 Jul 2000

☐ This action is **FINAL**.

☐ Since this application is in condition for allowance except for formal matters, **prosecution as to the merits is closed** in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11; 453 O.G. 213.

A shortened statutory period for response to this action is set to expire 3 month(s), or thirty days, whichever is longer, from the mailing date of this communication. Failure to respond within the period for response will cause the application to become abandoned. (35 U.S.C. § 133). Extensions of time may be obtained under the provisions of 37 CFR 1.136(a).

## Disposition of Claims

☒ Claim(s) 1-17 is/are pending in the application.

Of the above, claim(s) \_\_\_\_\_ is/are withdrawn from consideration.

☐ Claim(s) \_\_\_\_\_ is/are allowed.

☒ Claim(s) 1-17 is/are rejected.

☐ Claim(s) \_\_\_\_\_ is/are objected to.

☐ Claims \_\_\_\_\_ are subject to restriction or election requirement.

## Application Papers

☒ See the attached Notice of Draftsperson's Patent Drawing Review, PTO-948.

☐ The drawing(s) filed on \_\_\_\_\_ is/are objected to by the Examiner.

☐ The proposed drawing correction, filed on \_\_\_\_\_ is ☐ approved ☐ disapproved.

☒ The specification is objected to by the Examiner.

☐ The oath or declaration is objected to by the Examiner.

## Priority under 35 U.S.C. § 119

☐ Acknowledgement is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d).

☐ All ☐ Some\* ☐ None of the CERTIFIED copies of the priority documents have been  
☐ received.

☐ received in Application No. (Series Code/Serial Number) \_\_\_\_\_.

☐ received in this national stage application from the International Bureau (PCT Rule 17.2(a)).

\*Certified copies not received: \_\_\_\_\_

☐ Acknowledgement is made of a claim for domestic priority under 35 U.S.C. § 119(e).

## Attachment(s)

☒ Notice of References Cited, PTO-892

☐ Information Disclosure Statement(s), PTO-1449, Paper No(s). \_\_\_\_\_

☐ Interview Summary, PTO-413

☒ Notice of Draftsperson's Patent Drawing Review, PTO-948

☐ Notice of Informal Patent Application, PTO-152

--- SEE OFFICE ACTION ON THE FOLLOWING PAGES ---

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### **DETAILED ACTION**

1. This communication is responsive to Response filed on 17 July 2000. Claim 17 is added. Claims 1-17 are pending.

#### ***Specification***

2. The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

3. Specification is objected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to enable one skilled in the art to which it pertains, or with which it is most nearly connected, to make and/or use the invention. The specification, in page 9, lines 16-18, states that the thickness A at the center of the pad is greater than the thickness B near the edge of the pad. However, in Fig. 2, the thicknesses A and B are not the thicknesses of the pad but thicknesses of a polishing table.

#### ***Claim Rejections - 35 USC § 112***

4. The following is a quotation of the second paragraph of 35 U.S.C. 112:

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The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

5. Claims 11-16 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.
6. Claim 11 recites the limitation "the pad" in line 7, claim 13 recites the limitations "the conditioning wheel" and "the polishing table" in line 2. There is insufficient antecedent basis for these limitations in the claims.

***Claim Rejections - 35 USC § 102***

7. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless --

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

8. Claims 1-17 are rejected under 35 U.S.C. 102(b) as being anticipated by Renteln.

Renteln discloses an arrangement 100 for chemical mechanical polishing a wafer 200 comprising means for polishing a wafer or a polishing pad 202, means for holding a wafer or a wafer carrier, means for determining whether the wafer is polishing in a center-offset manner and means for conditioning means for polishing or conditioning

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device 220, a supply to supply conditioning material to the polishing pad. Renteln also discloses a method for polishing a wafer comprising means for using polishing pad, polishing the wafer at a position relative to the center, means for determining the wafer is being polished in a center-offset manner and means for conditioning the pad, arranging the condition device over the pad relative to center of polishing table, inspecting wafer during polishing process, wherein determining includes removing the wafer from the carrier and inspecting the wafer, the condition device comprises thinning the center and edge of the pad or altering the thickness of the pad at one location (note Fig. 3, col. 3, line 52, to col. 5, line 4).

### ***Conclusion***

9. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Breivogel et al, Sugiyama et al, Muroyama et al and Cesna are cited to show method and apparatus for conditioning a polishing pad.

10. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Dung Van Nguyen whose telephone number is (703) 305-0036.

DVN

August 25, 2000

  
Timothy V. Eley  
Primary Examiner